

规格书编号 SPEC NO: HDFB03RSSB5SP04

产品规格书 SPECIFICATION

CUSTOMER 客户:			
PRODUCT 产品:	SAW FILTER		
MODEL NO 型 号:	HDFB03RSS-B5		
MARKING 印字:	B089		
PREPARED 编 制:	CHECKED 审 核:		
APPROVED 批 准:	DATE日期: 2016-11-25		

客户确认 CUSTOMER RECEIVED:			
审核 CHECKED	批准 APPROVED	日期 DATE	

无锡市好达电子有限公司 Shoulder Electronics Limited

Factory Address: NO. 115, Gaoyun Road, Binhu Economic & Technology Development Area, Wuxi,Jiangsu, China. Tel: 86-510-85629111Country of origin: China

SAW FILTER

更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark
2015-10-12	SP00	HDFB03RSS -B5		NEW SPEC.	
2016-05-06	SP01	HDFB03RSS -B5		Complete specifications. Add product application, reliability and other information.	
2016-08-23	SP02	HDFB03RSS -B5		Change carrier tape size. Carrier tape encryption.	10. TAPE SPECIFICATIONS [Figure 1] Carrier Tape Dimensions
2016-11-18	SP03	HDFB03RSS -B5		Optimize insertion loss.	5. ELECTRICAL SPECIFICATION
2016-11-25	SP04	HDFB03RSS -B5		Correction device size. Thickness changed from 0.5max. to 0.65max	2. Package Dimension

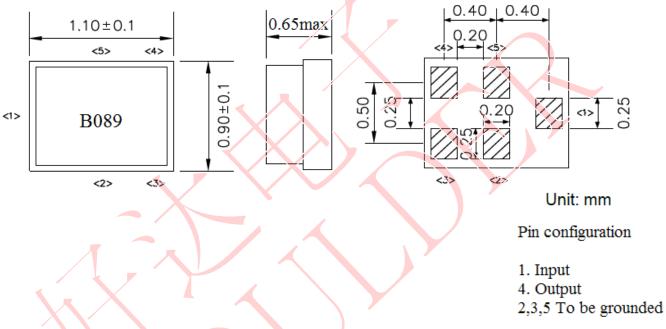
HDFB03RSS-B5

SAW FILTER

1. Application

- Low-loss RF filter for mobile telephone GSM 1800 systems.
- Impedance 50 ohm input and output.
- Unbalanced to unbalanced operation.
- Useable passband 60MHz.
- RoHS compatible.

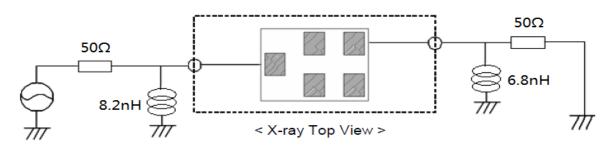
2. DIMENSION (PKG SIZE 1.1 x 0.9mm)



3. Maximum Rating

Items	Conditions		
Operation temperature rang	-30°C ~+85°C		
Storage temperature rang	-40°C ∼ +85°C		
ESD voltage	ESD(MM): 50VDC		
Sensitive discharge device	ESD(HBM) : 175VDC		
DC Voltage VDC	5V		
Max Input Power	15dBm 2000h		
Moisture Sensitivity Level	MSL 2		

4. Test Circuit



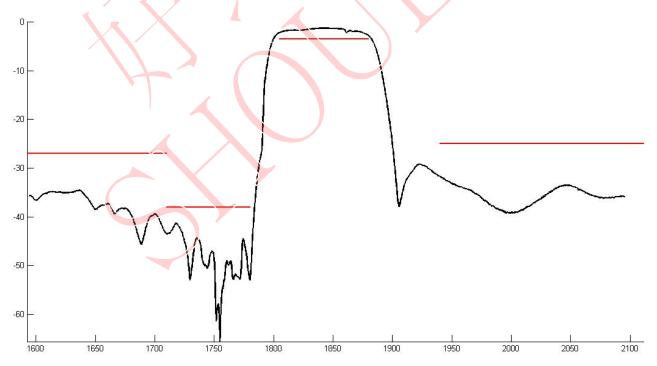
SAW FILTER

5. ELECTRICAL SPECIFICATION

Table1. Electrical Specification

Temperatur	re range for spe	ecification: $T = -20$ -	~ +80℃			
Terminating source impedance:		lance: $Zs = 50$	$Zs = 50\Omega / / 8.2$ nH unbalanced			
Terminating load impedance:		nce: $Zl = 50!$	$Zl = 50\Omega //6.8$ nH unbalanced			
Input powe	15dBm	15dBm 2000h				
Item Condition		Condition	Specification		Unit	
		(MHz)	Min	Тур	Max	
Insertion loss 1805~188		1805~1880	-	2.0	3.2	dB
Amplitud	e Ripple	1805~1880		1.0	2.4	dB
VSWR	Input	1805~1880	-	1.8	2.2	-
	Output		-	1.8	2.2	- ,
Absolute	e attenuation	40~1710	27	35		dB
		1712.4~1782.6	42	44	-	dB
		1940~2400	25	32	_	dB
		2400-2500	32	38		dB
		2500~8000	23	26	-	dB

6. Typical frequency response



7. ENVIRONMENTAL CHARACTERISTICS

7.1 High temperature exposure

Subject the device to $+85^{\circ}$ C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 5.

7.2 Low temperature exposure

Subject the device to -40° C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 5.

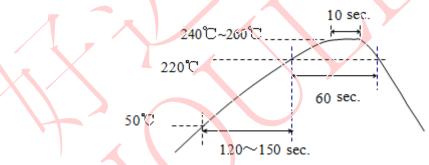
7.3 Temperature cycling

Subject the device to a low temperature of -40° C for 30 minutes. Following by a high temperature of $+85^{\circ}$ C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 5.

- 7.4 Resistance to solder heat
 - 1, immerge the solder bath at 260° C for 10 sec.
 - 2, the iron at 370°C for 3 sec
- 7.5 Solderability

Submerge the device terminals into the solder bath at 245° C $\pm 5^{\circ}$ C for 5s. More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 5.

7.6 Reflow soldering



The specimen shall be passed through the reflow furnace with the condition shown in the above profile for 1 time.

The specimen shall be stored at standard atmospheric conditions for 1h, after which the measurement shall be made. Test board shall be 1.6 mm thick. Base material shall be glass fabric base epoxy resin.

7.7 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 5.

7.8 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 5.

8. REMARK

8.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of

the component. Please avoid static voltage.

8.2 Ultrasonic cleaning

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Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

8.3 Soldering

SAW FILTER

Only pad component may be solded. Please avoid soldering another part of component.

9. Packing

- 9.1 Dimensions
 - (1) Carrier Tape: Figure 1
 - (2) Reel: Figure 2

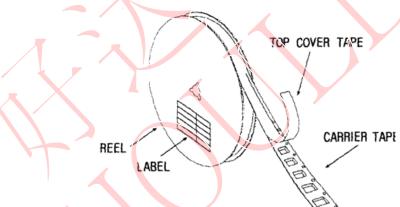
(3) The product shall be packed properly not to be damaged during transportation and storage.

9.2 Reeling Quantity

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10000 pcs/reel φ 178mm
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9.3 Taping Structure

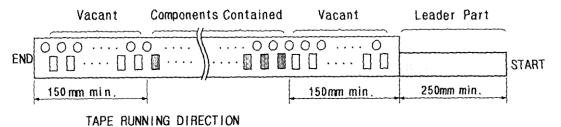
(1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
Marking	
User Product Name	
Quantity	
Lot No.	

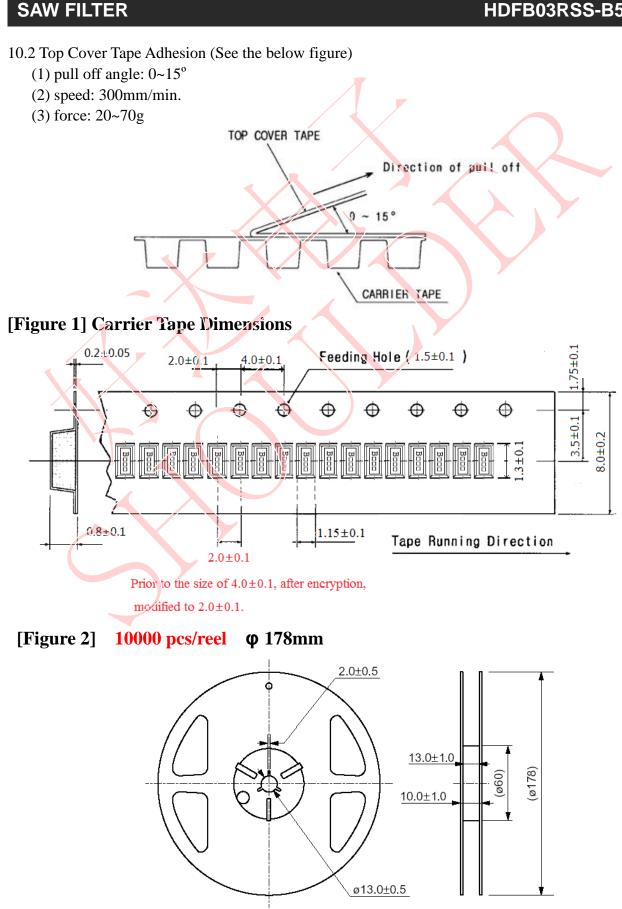
(3) Leader part and vacant position specifications.



10. TAPE SPECIFICATIONS

10.1 Tensile Strength of Carrier Tape: 4.4N/mm width

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ø178 Reel Dimension

(in mm)

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